

1. A method of forming an integrated circuit package, the method comprising:
forming a lead frame having a plurality of conductors and at least one alignment feature
electrically isolated from the plurality of conductors;
coupling at least some of the plurality of conductors to a semiconductor die; and
encapsulating the semiconductor die and a portion of the lead frame with an insulating material.

2. The method of claim 1, further comprising removing the at least one alignment feature.

3. A method of forming an integrated circuit package, the method comprising:
providing a plurality of conductors and at least one alignment feature;
coupling at least some of the plurality of conductors to a semiconductor die; and
encompassing the semiconductor die, the at least one alignment feature, and a portion of each of
the plurality of conductors with an insulating material.

4. (Amended) A method of forming and testing an integrated circuit package, the method comprising:
providing a plurality of conductors and at least one alignment feature;
electrically coupling at least some of the plurality of conductors to a semiconductor die;
encompassing the semiconductor die, the at least one alignment feature, and a portion of each of
the plurality of conductors with an insulating material;
coupling the at least one alignment feature encompassed by [an] the insulating material with a
portion of [the] a testing device; and
testing the integrated circuit package through at least some of the electrically coupled conductors.

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